



How To Order

RI - (1) (2) / (3) - (4) / (5)

(1) No. of contact (2) P : Plug S : Socket

(3) 1 : Single Row / 2 : Double Row / 3 : 0.3" Row to Row Pitch /
4 : 0.4" Row to Row Pitch / 6 : 0.6" Row to Row Pitch

(4) Contact Plating

GF : Gold Flash / T200 : Tin 200 μ "/SG : Select Gold Flash/

S10 : Select Gold plated 10 μ "/S15 : Select Gold plated

15 μ "/S30 : Select Gold plated 30 μ "

(5) Blanked : Dip Solder Type / W : Wire Wrapping / D : SMD Type

E : Empty , No Bar

Ex. RI - 08S/1 - SG

Round IC Socket 8Pin , Socket/ **Single** Row , Select Gold Flash

Ex. RI - 12S/1 - SG

Round IC Socket 12Pin , Socket/ **Single** Row , Select Gold Flash

Technical Data

Material:

Pin(outer sleeve): Brass, machined CuZn38Pb2

Clip(contact 4 fin): Phosphor/Bronze heat treated

Plating(outer sleeve):

Tin plated: 2 μ m/80u" Ni, 5 μ m/200u" Sn

Gold Plated: 2 μ m/80u" Ni, Full gold

Insulator(black): Glass filled thermoplastic polyester
UL94V-0

Electrical:

Current rating: 3Amps/contact max.

Contact resistance: $\leq 4\text{m}\Omega$ /contact

Insulation resistance: $\geq 1000\text{M}\Omega$ at V=100V

Operating voltage: 60VAC/DC

Mechanical:

Operating temperatures: Gold Plated: -55°C to +125°C

Tin plated: -40°C to +105°C

Soldering temperature: +260°C, 10s max.

				FLYING 汎翊國際有限公司			
				TOLERANCES ARE	APPROVED	DATE	DRAWING NO
				X. ±0.3	CHECKED		NAME
				X.X ±0.2			
				X.XX ±0.15	DATE		SCALE
				X.XXX ±0.10			
				X.XXX ±0.10	DRAWN		UNIT
				ANGLE ±5°			
					DATE		REV
					Lee 2008/04/06		A
					MM		1:1
					SER		REVISIONS
					Lee		CHK
					2007/07/08		DATE
					新圖發行		REVISIONS